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503.41877VX1

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: TAKAHASHI, et al.
Serial No.: 10/602,713
Filed: June 25, 2003
For: SOLVENT-FREE THERMOSETTING RESIN COMPOSITION,
PROCESS FOR PRODUCING THE SAME, THE PRODUCT
THEREFROM
Group: 1712
Examiner: M. Feely

AMENDMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

March 28, 2005

Sir:

In response to the Office Action mailed January 26, 2005, please amend the above-identified application as listed in the following, and as set forth on the following pages:

Amendments to the Specification;

Amendments to the Drawings;

Amendments to the Claims; and

As An Appendix, a replacement sheet of drawings of Fig. 4.

Remarks are included following the amendments.